


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/17/9820	
1.3 Title of PCN	Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in UFQFPN 4x4 package	
1.4 Product Category	UFQFPN 4x4 COL packaged products	
1.5 Issue date	2017-02-17	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	FRANK WOLINSKI
2.1.2 Phone	+49 89460062287
2.1.3 Email	frank.wolinski@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Daniel COLONNA
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer...)	Stats ChipPAC Shanghai China (SCC), Stats ChipPAC Jiangyin China (JSCC)

4. Description of change

	Old	New
4.1 Description	Current location : Stats ChipPAC Shanghai China (SCC)	Transfer from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) location. See more information on PCN 9820 – Additional information document attached.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Change lead shape : with neck design. See in PCN 9820 – Additional information document attached. No change in fit, function, reliability or process ability.	

5. Reason / motivation for change

5.1 Motivation	Due to Shanghai China site closure, production is relocated to Jiangyin China site. This Product Change Notification (PCN) concerns only UFQFPN 4x4 COL packaged products.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	Traceability is described in PCN 9820_Additional information attached document.
------------------------	---

7. Timing / schedule

7.1 Date of qualification results	2017-06-02
7.2 Intended start of delivery	2017-07-02
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	9820 PCN9820_RERMCD1623- UQFN4x4 COL JSCC- MCD QA reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-02-17

9. Attachments (additional documentations)

9820 Public product.pdf
9820 PCN9820_Additional information.pdf
9820 PCN9820_RERMCD1623- UQFN4x4 COL JSCC- MCD QA reliability plan.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F031G4U6	
	STM32F042G4U6	
	STM8L151G3U6	
	STM8L151G3U6TR	
	STM8TL52G4U6	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics – All rights reserved